

Abstract

A circuit board assembly is provided having a multiple layer printed circuit board. A ceramic surface mounted device is provided having first and second end caps. First and second electrically conductive pads support respective first and second ends of the surface mounted device above the printed circuit boards. The pads are soldered to the end caps. One of the pads supplies power and the other pad serves as a ground. A heat sink is positioned adjacent the printed circuit board opposite the pads and is separated from the printed circuit board by a thermally conductive electrically insulating adhesive. A plurality of thermal vias are deposited in each of the pads thermally connecting the first and second pads with respective third and fourth pads generally on the opposite side of the circuit board.

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